

Product/Process Change Notification

PCNN° 2023-111-B !! UPDATE !!

- Updated information marked in **BLUE TYPE**
- Original PCN N° 2023-111-A dated 2024-07-25

Dear customer,

please find attached an updated PCN for your attention:

Several changes affecting the 4-Kbit to 256-Kbit Industrial Grade F-RAM products

If you have any questions, please do not hesitate to contact your local sales office.

Infineon Technologies AG

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Products affected

Please refer to attached affected product list PCN_2023-111-B_[customer-no].pdf

Detailed change information

Subject: Several changes affecting the 4-Kbit to 256-Kbit Industrial Grade F-RAM products

Reason/Motivation: New design revision that incorporates advantages of Infineon's Excelon™ architecture to the 4-Kbit to 64-Kbit devices. Migrating to the new die revision will enable customers to benefit from continued product supply and long term technical support on these products.

Ensure delivery capability by establishing alternative assembly and packaging components to assure continuity of supply and enable flexible manufacturing. Due to continuously raising demand for Infineon F-RAM products, we have extended our final test capacity to Greatek Taiwan as additional location of our BE test cluster, to assure continuity of supply.

Description		Old	New
Design changes in active elements	DESIGN: 4-Kbit, 16-Kbit & 64-Kbit F-RAM	(only applicable to the memory array tile die)	4-Kbit, 16-Kbit & 64-Kbit F-RAM:
	Old design (memory array and architecture)	AND New design (memory array with improved architecture)	
Design changes in routing	DESIGN: 4-Kbit, 16-Kbit & 64-Kbit F-RAM:	(only applicable to the memory array tile die)	4-Kbit, 16-Kbit & 64-Kbit F-RAM:
	Old routing without scan ATPG	AND New routing with scan ATPG and improved ECC	

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	DESIGN: 4-Kbit, 16-Kbit & 64-Kbit F-RAM: Die shrink (only applicable to the memory array tile die) Old die size	4-Kbit, 16-Kbit & 64-Kbit F-RAM: (only applicable to the memory array tile die) Old die size AND New die size based on design optimization.
	PROCESS - ASSEMBLY: 4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: Change of wire bonding (only applicable to UTAC's PG-DSO-8-802): CuPd	4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: (only applicable to UTAC's PG-DSO-8-802): CuPd AND CuPdAu
	PROCESS - ASSEMBLY: 4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: Change of mold compound / encapsulation material (only applicable to UTAC's PG-DSO-8-802): G600 (only CuPd wire)	4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: (only applicable to UTAC's PG-DSO-8-802): G600 (only CuPd wire) AND G633CB (only CuPdAu wire)
	PROCESS - ASSEMBLY: 4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: Change of specified assembly process sequence (deletion and/or additional process step) (only applicable to UTAC's PG-DSO-8-802): Old dejunk plating and trim & form process (only CuPd wire)	4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: (only applicable to UTAC's PG-DSO-8-802): Old dejunk plating and trim & form process (only CuPd wire) AND New dejunk plating and trim & form process (only CuPdAu wire)
	TEST FLOW: 4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: Move of all or part of electrical wafer test and/or final test to a different test site (only applicable to PG-DSO-8-802) UTAC Thai Ltd (UTL1), Bangkok, Thailand	4-Kbit, 16-Kbit, 64-Kbit, 128-Kbit & 256-Kbit F-RAM: (only applicable to PG-DSO-8-802) UTAC Thai Ltd (UTL1), Bangkok, Thailand AND Greatek Electronics Inc, Zhunan, Taiwan

Product identification

Traceability assured via date code.
No change in SP ordering number.

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Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in form, fit and function expected.

Attachments

PCN_2023-111-B_[customer-no].pdf affected product list

Time schedule

	2023-111-A	2023-111-B
Final qualification report	available	available
First samples available	on request	on request
Intended start of delivery [1]	2025-01-31	2025-01-31
Last order date (LOD) [2]	2025-01-31	2025-01-31
Last delivery date (LDD) [3]	2025-07-31	2025-07-31

[1] Provided date or earlier after customer approval.

[2] Last date where orders for unchanged products will be accepted.

[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

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